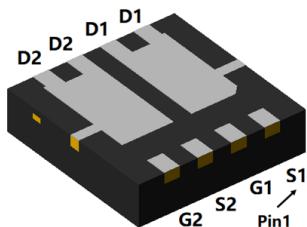
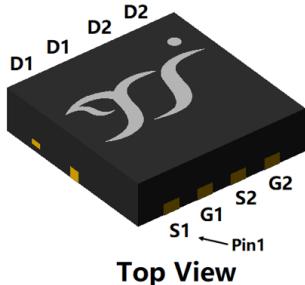
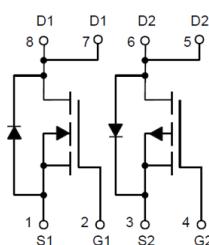


N-Channel and P-Channel Complementary MOSFET


Bottom View

DFN3333-8L

Product Summary

NMOS

- V_{DS} 30V
- I_D 28A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<18m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<30m\Omega$

PMOS

- V_{DS} -30V
- I_D -20A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) $<40m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) $<60m\Omega$
- 100% EAS Tested

General Description

- Trench Power LV MOSFET technology
- High density cell design for low $R_{DS(ON)}$
- High Speed switching
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Wireless charger
- Load switching
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	NMOS	PMOS	Unit
Drain-source Voltage		V_{DS}	30	-30	V
Gate-source Voltage		V_{GS}	± 20	± 20	V
Drain Current	$T_A=25^\circ C$	I_D	7.5	-5	A
	$T_A=100^\circ C$		4.5	-3	
	$T_C=25^\circ C$		28	-20	
	$T_C = 100^\circ C$		17.5	-12	
Pulsed Drain Current ^A		I_{DM}	60	-40	A
Avalanche energy ^B		EAS	16	16	mJ
Total Power Dissipation ^C	$T_A=25^\circ C$	P_D	2	2	W
	$T_A=100^\circ C$		0.8	0.8	
	$T_C=25^\circ C$		27	27	
	$T_C = 100^\circ C$		11	11	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	-55~+150	°C

■ Thermal resistance

Parameter	Symbol	NMOS		PMOS		Units
		Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient ^D	$R_{\theta JA}$	50	62.5	50	62.5	°C/W
Thermal Resistance Junction-to-Case		3.5	4.5	3.5	4.5	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQ4606B	F1	Q4606B	5000	10000	100000	13" reel



YJQ4606B

■ NMOS Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, T_J=150^\circ\text{C}$	-	-	100	
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.2	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=14\text{A}$	-	14	18	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	-	23	30	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=14\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.2	V
Gate resistance	R_{G}	$f=1\text{MHz}$	-	2	-	Ω
Maximum Body-Diode Continuous Current	I_{S}		-	-	28	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	380	-	pF
Output Capacitance	C_{oss}		-	75	-	
Reverse Transfer Capacitance	C_{rss}		-	60	-	
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, I_{\text{D}}=10\text{A}$	-	12.5	-	nC
Gate-Source Charge	Q_{gs}		-	2.8	-	
Gate-Drain Charge	Q_{gd}		-	2.5	-	
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=10\text{A}, \text{di}/\text{dt}=100\text{A/us}$	-	1.7	-	nC
Reverse Recovery Time	t_{rr}		-	18	-	ns
Turn-on Delay Time	$t_{\text{D(on)}}$		-	5	-	ns
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=15\text{V}, I_{\text{D}}=10\text{A}$ $R_{\text{GEN}}=3\Omega$	-	31	-	
Turn-off Delay Time	$t_{\text{D(off)}}$		-	15	-	
Turn-off fall Time	t_{f}		-	23	-	



YJQ4606B

■ PMOS Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
		$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, T_J=150^\circ\text{C}$	-	-	-100	
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.5	-2.4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-10\text{A}$	-	31	40	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	45	60	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-10\text{A}, V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
Gate resistance	R_{G}	$f=1\text{MHz}$	-	15	-	Ω
Maximum Body-Diode Continuous Current	I_{S}		-	-	-20	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	490	-	pF
Output Capacitance	C_{oss}		-	75	-	
Reverse Transfer Capacitance	C_{rss}		-	60	-	
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-10\text{A}$	-	9	-	nC
Gate-Source Charge	Q_{gs}		-	2.5	-	
Gate-Drain Charge	Q_{gd}		-	2.3	-	
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=-10\text{A}, \text{di}/\text{dt}=100\text{A}/\text{us}$	-	15	-	nC
Reverse Recovery Time	t_{rr}		-	35	-	ns
Turn-on Delay Time	$t_{\text{D}(\text{on})}$	$V_{\text{GS}}=-10\text{V}, V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-10\text{A}$ $R_{\text{GEN}}=2.5\Omega$	-	9	-	ns
Turn-on Rise Time	t_{r}		-	3.5	-	
Turn-off Delay Time	$t_{\text{D}(\text{off})}$		-	30	-	
Turn-off fall Time	t_{f}		-	18	-	

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. NMOS: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_{\text{G}}=25\Omega$, $L=0.5\text{mH}$, $\text{IAS}=8\text{A}$.
PMOS: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=25\Omega$, $L=0.5\text{mH}$, $\text{IAS}=-8\text{A}$.
- C. P_d is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of $R_{\theta,\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^\circ\text{C}$.
The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.



YJQ4606B

■ NMOS Typical Electrical and Thermal Characteristics Diagrams

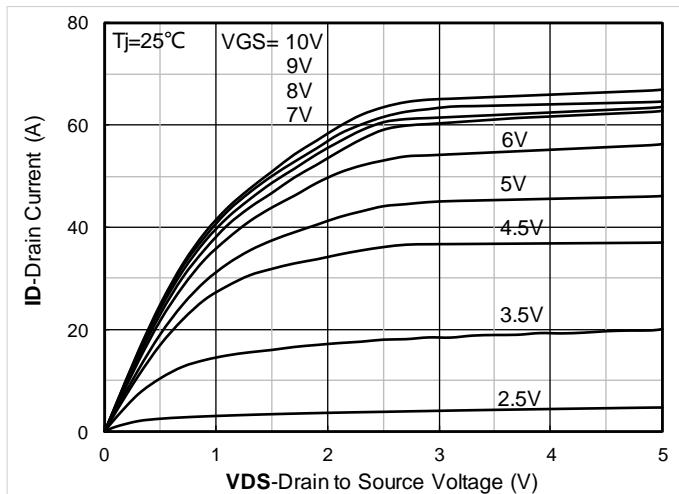


Figure 1. Output Characteristics

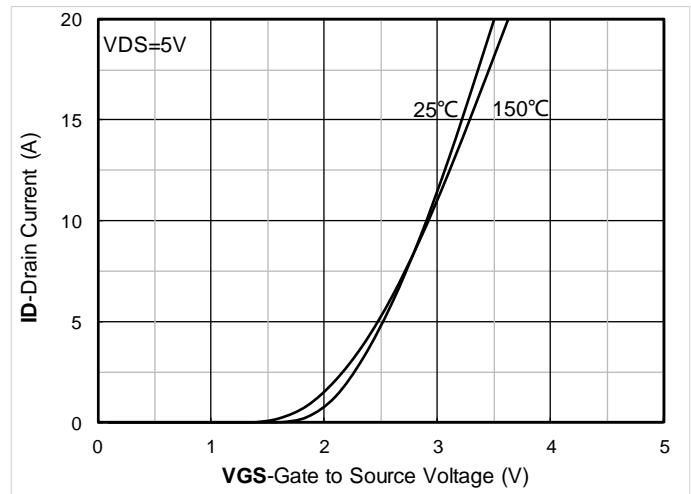


Figure 2. Transfer Characteristics

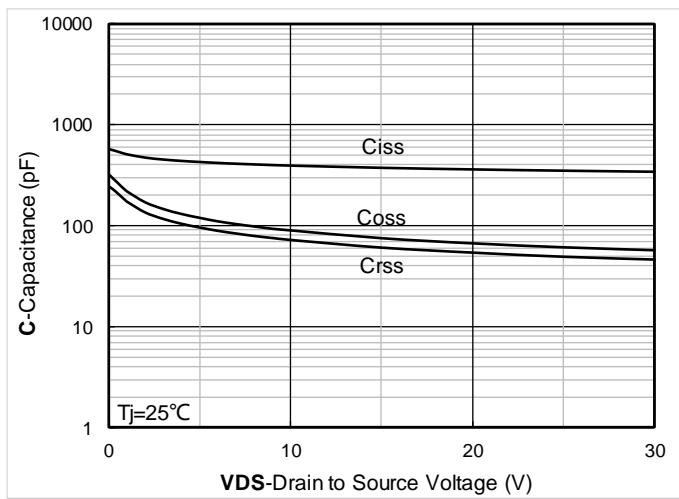


Figure 3. Capacitance Characteristics

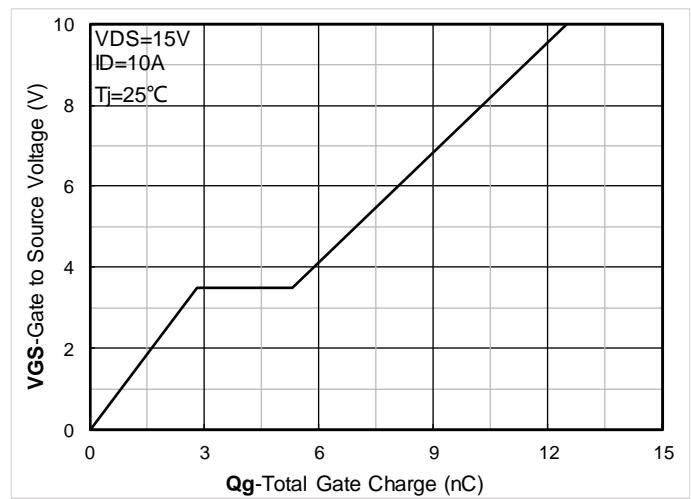


Figure 4. Gate Charge

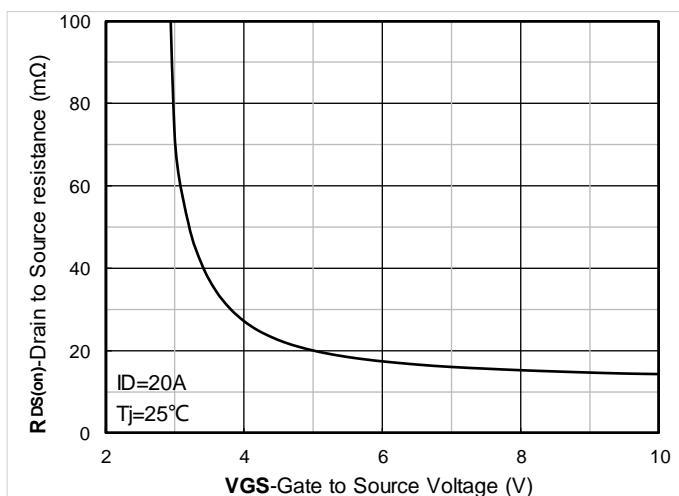


Figure 5. On-Resistance vs Gate to Source Voltage

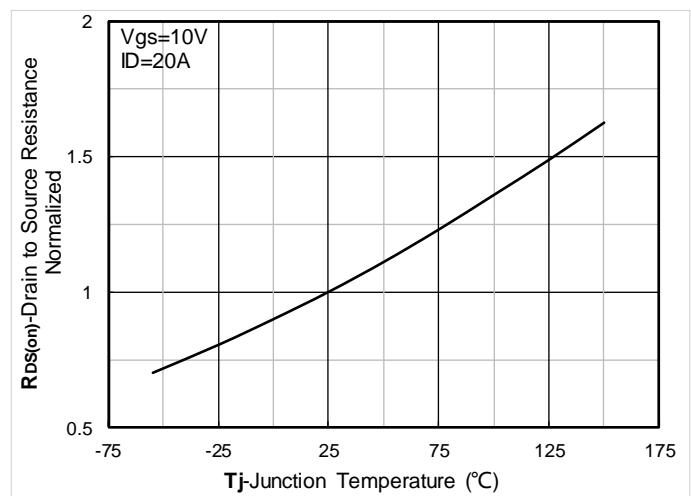


Figure 6. Normalized On-Resistance

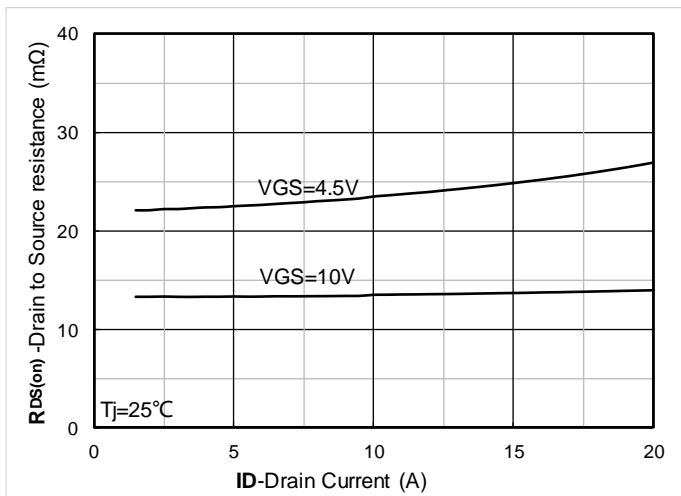


Figure 7. RDS(on) VS Drain Current

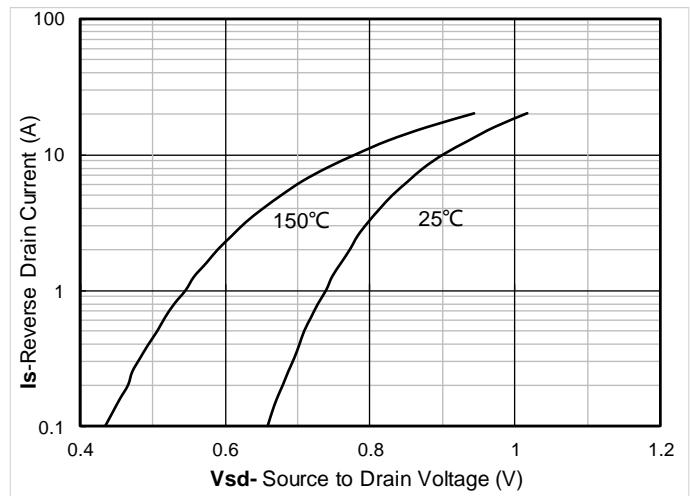


Figure 8. Forward characteristics of reverse diode

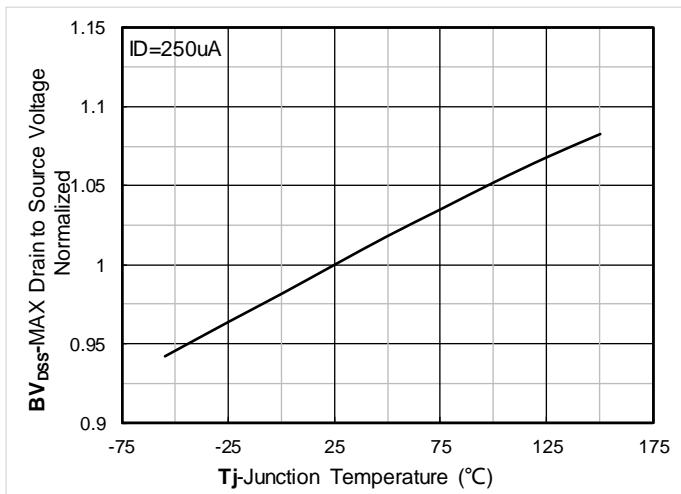


Figure 9. Normalized breakdown voltage

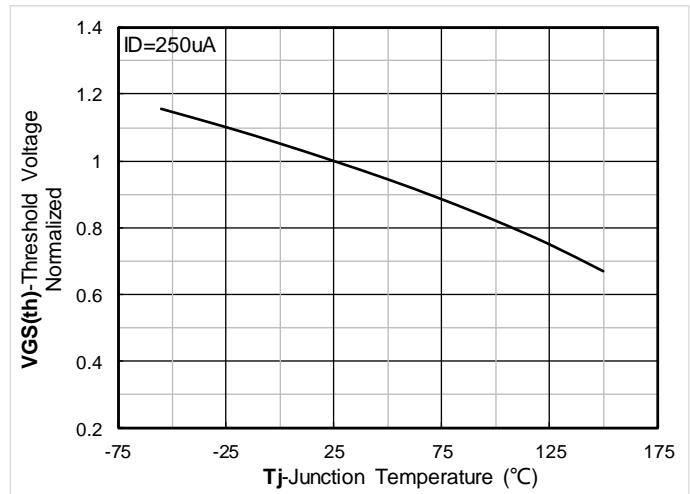


Figure 10. Normalized Threshold voltage

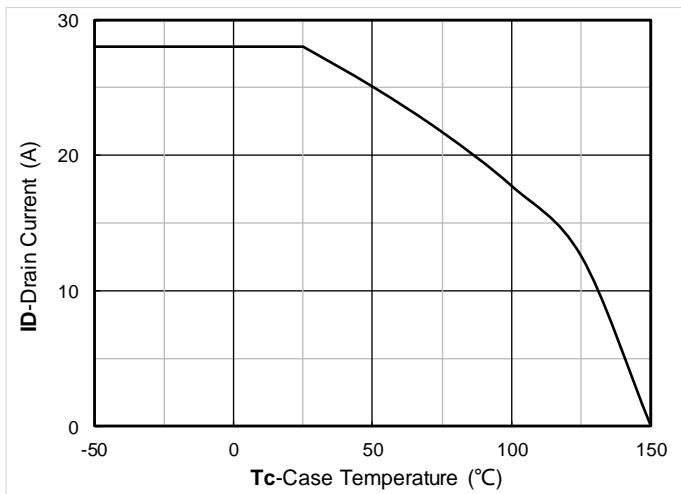


Figure 11. Current dissipation

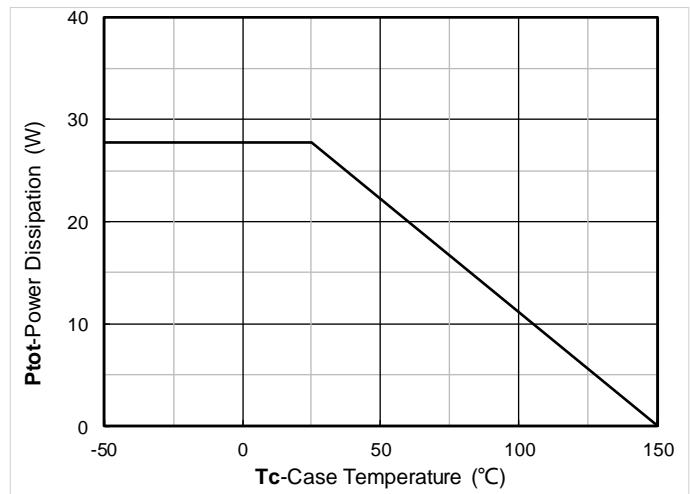


Figure 12. Power dissipation

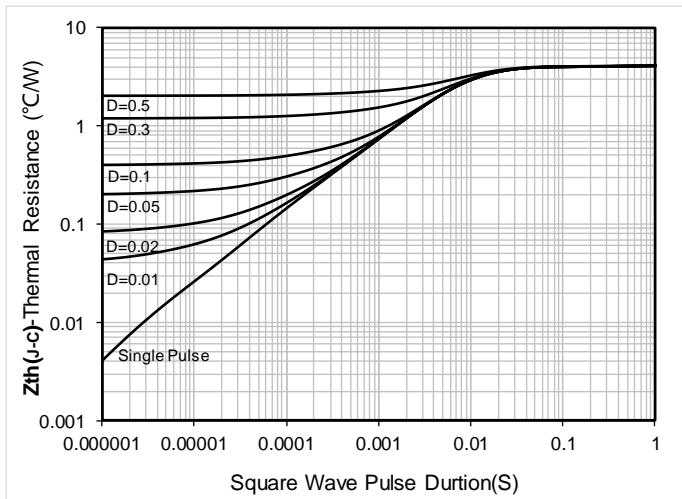


Figure 13. Maximum Transient Thermal Impedance

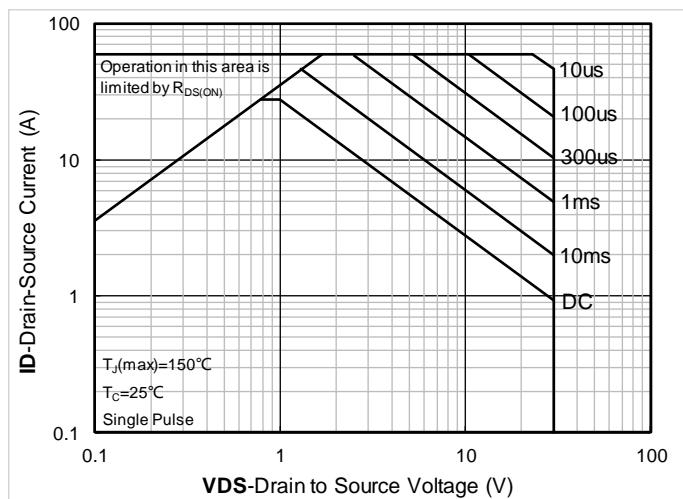


Figure 14. Safe Operation Area

■ PMOS Typical Electrical and Thermal Characteristics Diagrams

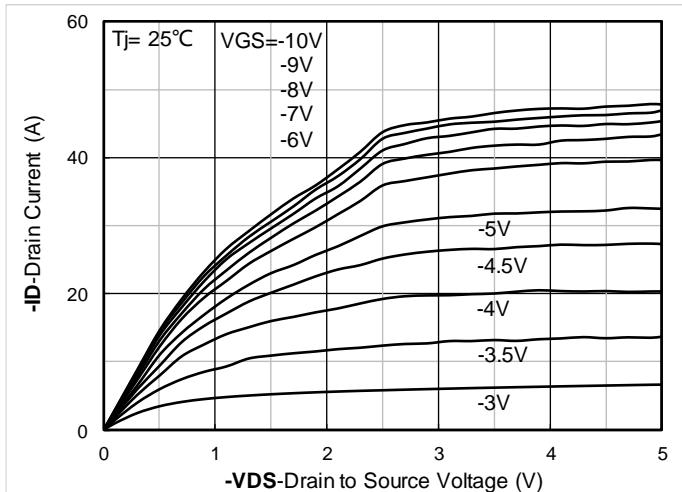


Figure 1. Output Characteristics

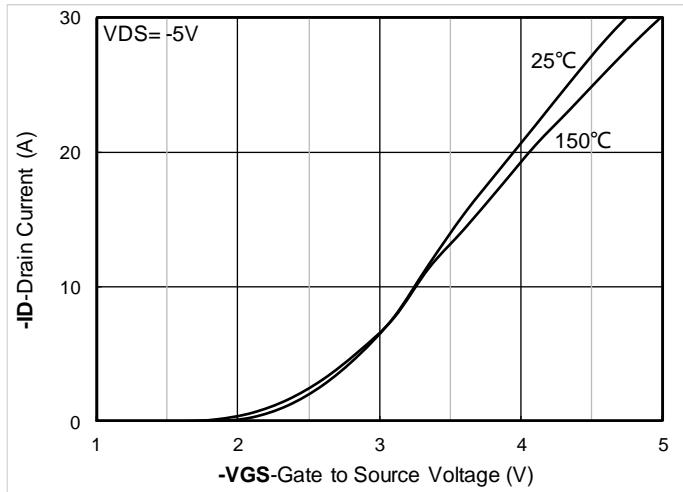


Figure 2. Transfer Characteristics

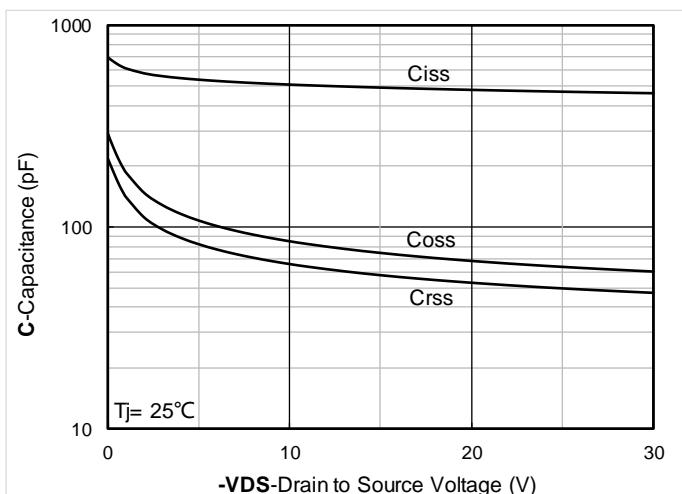


Figure 3. Capacitance Characteristics

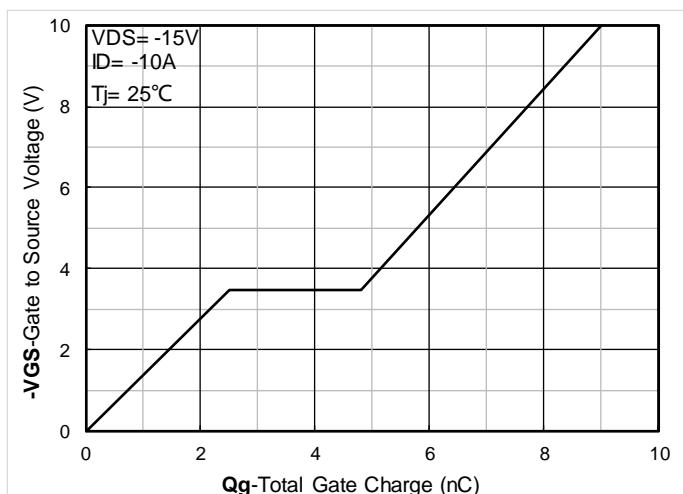


Figure 4. Gate Charge



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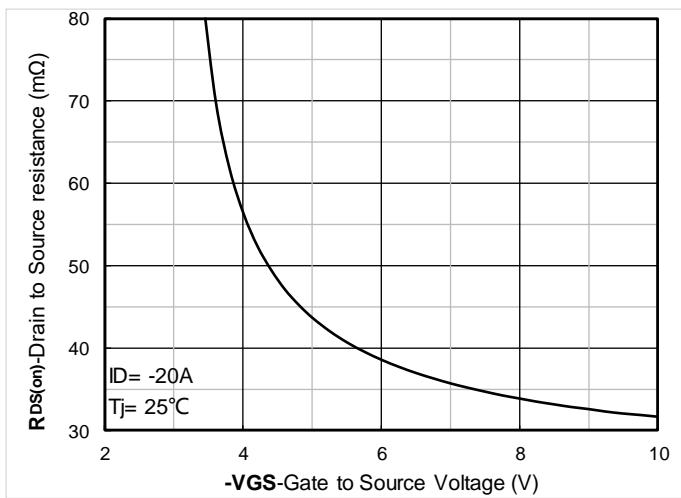


Figure 5. On-Resistance vs Gate to Source Voltage

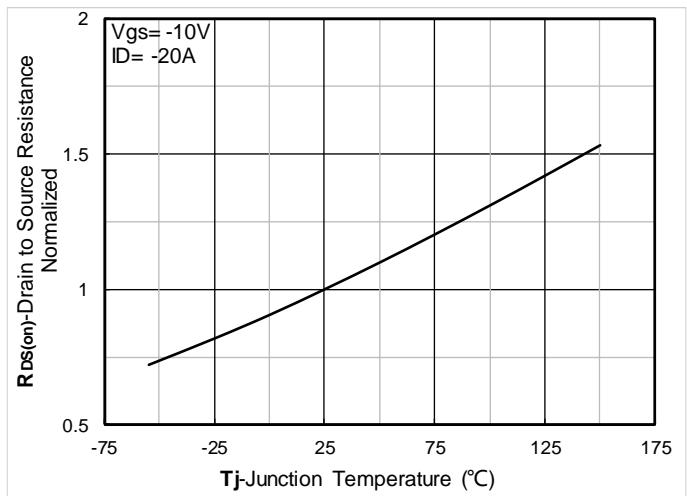


Figure 6. Normalized On-Resistance

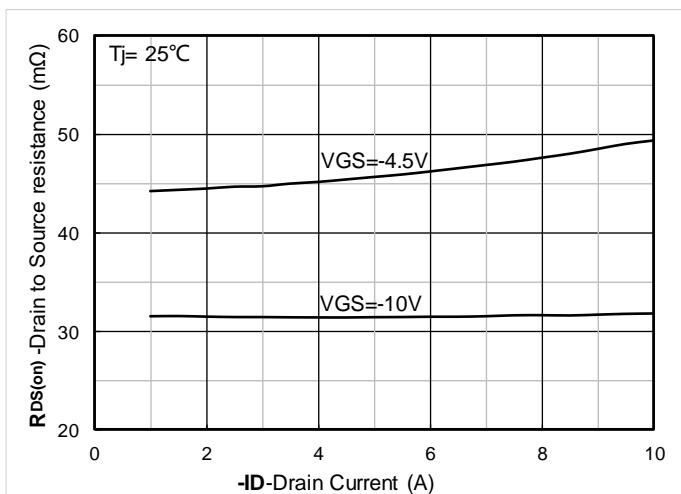


Figure 7. RDS(on) VS Drain Current

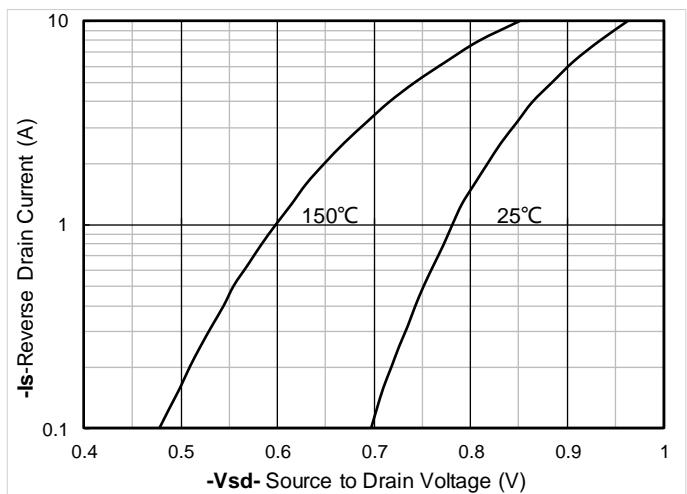


Figure 8. Forward characteristics of reverse diode

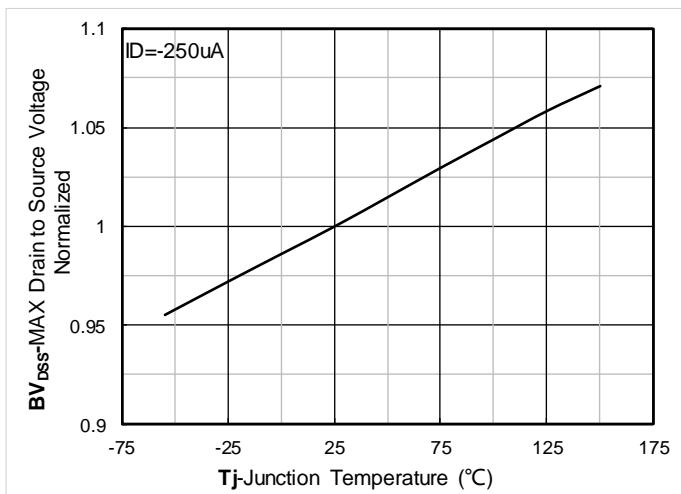


Figure 9. Normalized breakdown voltage

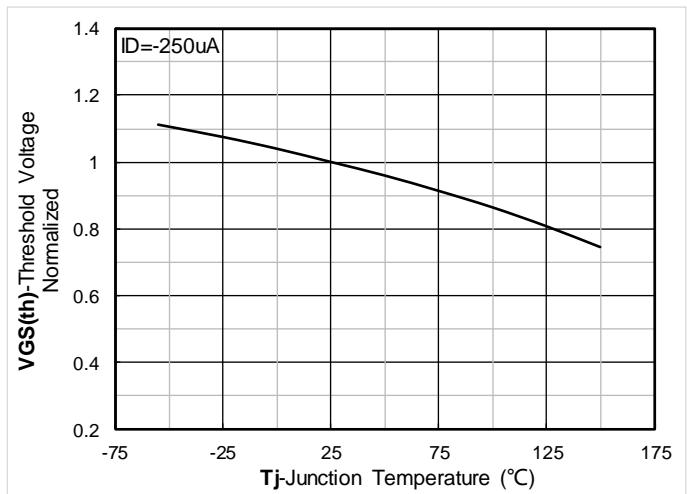


Figure 10. Normalized Threshold voltage

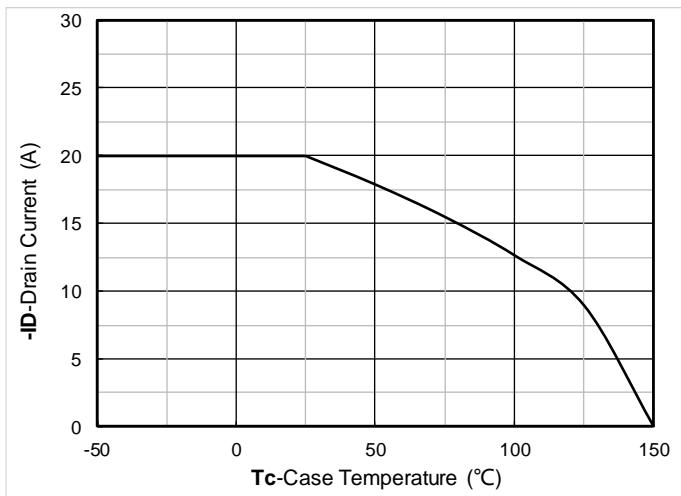


Figure 11. Current dissipation

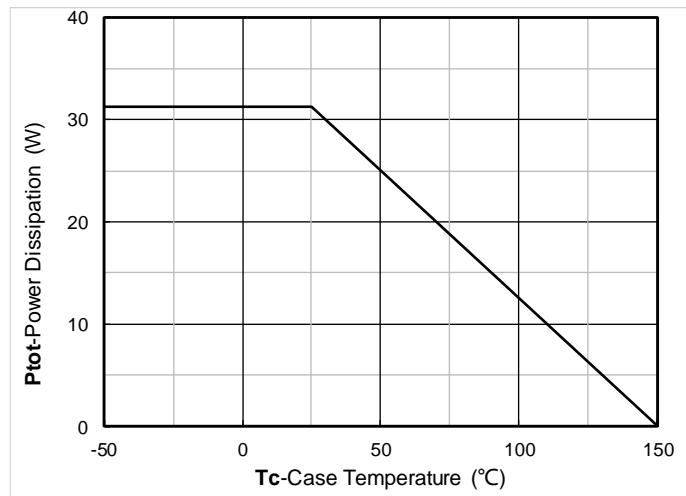


Figure 12. Power dissipation

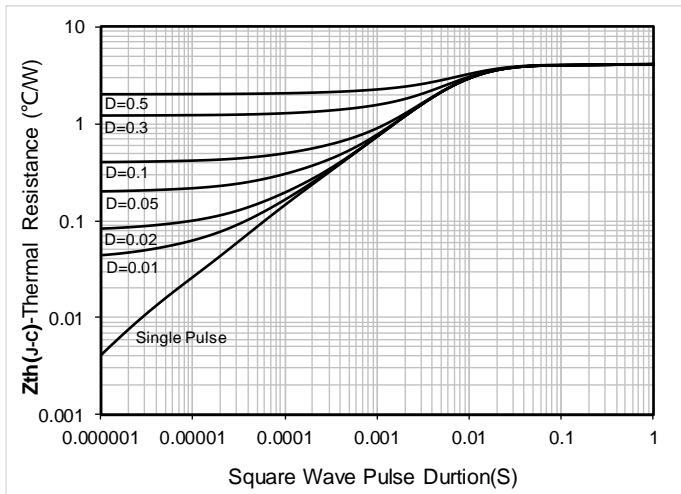


Figure 13. Maximum Transient Thermal Impedance

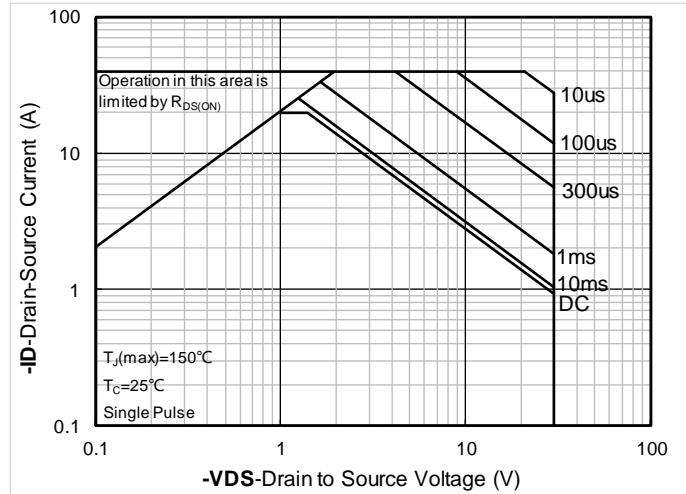
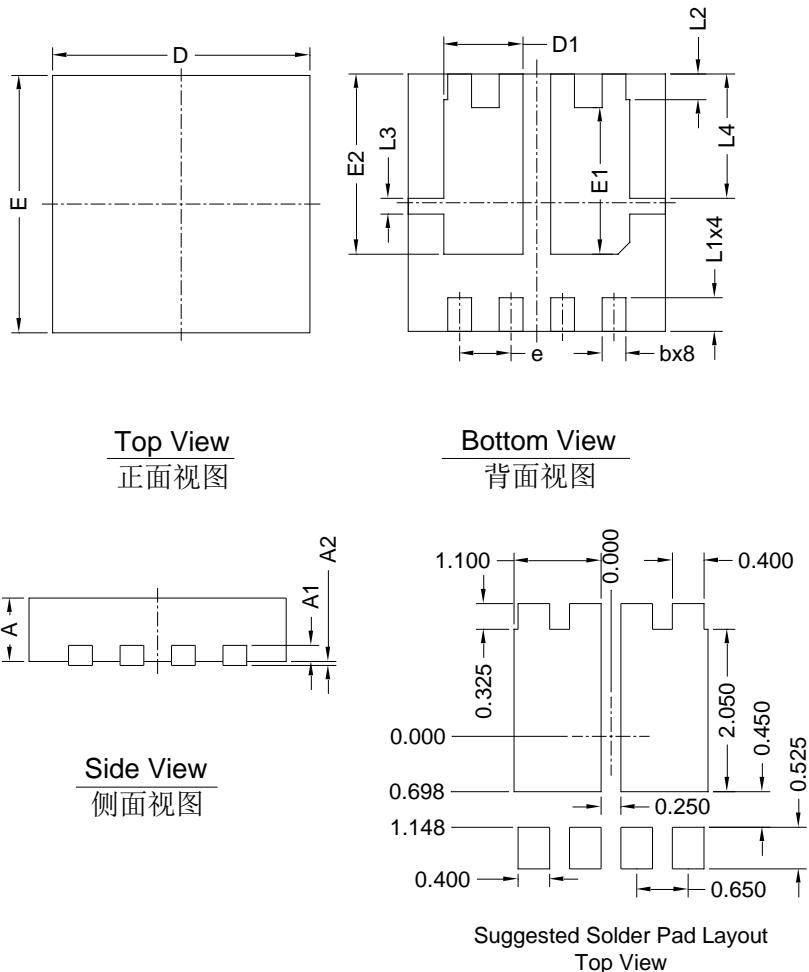


Figure 14. Safe Operation Area



■ DFN3333-8L-B-0.8MM Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	3.15	3.25	3.35
E	3.15	3.25	3.35
A	0.70	0.80	0.90
A1		0.20 BSC	
A2			0.10
D1	0.90	1.00	1.10
E1	1.75	1.85	1.95
E2	2.175	2.275	2.375
L1	0.325	0.425	0.525
L2		0.325 BSC	
L3		0.200 BSC	
L4		1.570 BSC	
b	0.20	0.30	0.40
e		0.65 BSC	

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use or sale.

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